

AMENDMENT TRANSMITTAL LETTER

Docket No.
M4065.0363/P363

Application No.
09/653,541

Filing Date
August 31, 2000

Examiner
Tu Tu V. Ho

Art Unit
2818

Applicant(s): Mark E. Tuttle

Invention: MAGNETIC SHIELDING FOR INTEGRATED CIRCUITS

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	-	=		x	0.00
Independent Claims	-	=		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00

☒ Large Entity

☐ Small Entity

☒ No additional fee is required for this amendment.

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Thomas J. D'Amico
Attorney Reg. No.: 28,371

Dated: August 5, 2002

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Docket No.: M4065.0363/P363
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Mark E. Tuttle

Application No.: 09/653,541

Filed: August 31, 2000

For: MAGNETIC SHIELDING FOR
INTEGRATED CIRCUITS

Group Art Unit: 2818

Examiner: Tu Tu V. Ho

11/a
G. Stang
8-8-02

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AMENDMENT

BOX: Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated May 3, 2002, rejecting claims 1-40 and 64-86, please amend the above-captioned U.S. Patent application as follows:

In the Claims

Please replace claims 32 and 70 with amended claims 32 and 70.

91 32. (amended) An integrated circuit chip containing structures which may be affected by external magnetic fields, said chip comprising a magnetic field shielding material in contact with a surface of said chip, wherein said surface is a back surface of the chip.

92 Sub. B4 > 70. (amended) A method of packaging a semiconductor device comprising:

electrically coupling a die carrier to a first surface of a die, said first surface being opposite to a second surface of said die; and